

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A leadframe packaging apparatus comprising:
a die;
at least two separated die pads each connected to a corresponding voltage level thereof;
a plurality of leadfingers including a signal leadfinger group, a power leadfinger group and a ground leadfinger group which are connected with each other through a plurality of metal wires; and
at least one passive component having two ends each connected to one of said two separated die pads;
wherein the passive component is connected to the signal leadfinger group.
2. (Original) The leadframe packaging apparatus of claim 1 wherein said voltage level is a power source voltage level and a ground voltage level.
3. (Original) The leadframe packaging apparatus of claim 2 wherein said power source voltage level and said ground voltage level is supplied by a printed circuit board, which is further fixedly connected with said leadframe packaging apparatus.

4. (Previously Presented) The leadframe packaging apparatus of claim 1 further comprising a busbar disposed between two non-adjacent leadfingers and extended from at least one of the non-adjacent leadfingers.

5-7. (Cancelled)

8. (Currently Amended) A packaging method for a leadframe packaging apparatus comprising steps as follows:

preparing an integrated circuit die;

adhering said integrated circuit die into least two separated die pads, each connected to a corresponding voltage level;

preparing at least one passive component having two ends, each connected to one of said two separated die pads respectively;

wirebonding said integrated circuit die;

preparing a molding compound for placing said integrated circuit die, said die pad, and said passive component therein;

defining ~~said~~ a plurality of leadfingers outside of said molding compound as first leadfinger sections and said leadfingers inside of said molding compound as second leadfinger sections, further said leadfingers includes a signal leadfinger group, a power leadfinger group and a ground leadfinger group; and

electrically connecting said first leadfinger sections with a printed circuit board and said second leadfinger sections with said integrated circuit die;

wherein the passive component is connected to the signal leadfinger group.

9. (Previously Presented) The packaging method of claim 8 further comprising a step of having a busbar disposed between two non-adjacent said second leadfinger sections.

10. (Previously Presented) The packaging method of claim 9, further comprising a step of preparing at least one passive component bridging one of two non-adjacent said second leadfinger sections and said busbar.

11. (Previously Presented) The packaging method of claim 8 further comprising a step of preparing at least one passive component bridging two adjacent said second leadfinger sections.

12. (Original) The packaging method of claim 8 further comprising a step of metalizing a bottom surface of said integrated circuit die before adhering said integrated circuit die into said die pad.

13. (Original) The packaging method of claim 8 wherein wirebonding said integrated circuit die is to wirebond a plurality of metal wires to said second leadfinger sections.

14. (Original) The packaging method of claim 8 wherein said leadfingers is made of an alloy.

15. (Previously Presented) The packaging method of claim 8 further comprising a step of preparing at least one passive component bridging two adjacent said first leadfinger sections.